



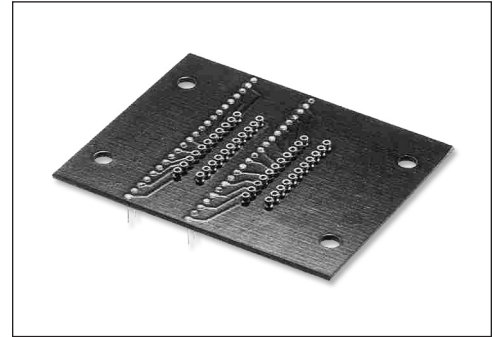
# P/N 97-68340 – 144-Pin QFP-to-PGA Adaptor for Motorola 68340

## FEATURES

- Convert surface mount QFP packages to a 15 x 15 PGA footprint
- Reduce costs by using less expensive QFP packages to replace PGA footprints in existing designs
- Pins are mechanically fastened and soldered to board using Aries' patented process, creating a reliable electrical connection and rugged contact
- Consult factory for panelized form or for mounting of consigned chips

## SPECIFICATIONS

- Adapter Body: FR-4, 0.062 [1.58] thick, with 1-oz. minimum Copper traces
- Pads: bare Copper protected with ENIG or immersion white tin to eliminate coplanarity concerns and solder bridges associated with hot air solder leveling
- Pins: Brass Alloy 360 1/2-hard per UNS C36000 ASTM-B16-00
- Pin Plating: 200µ [5.08µ] min. Tin per ASTM B 545 Type 1 or Tin/Lead 93/7 per ASTM B 545 over 100µ [2.54µ] Nickel per SAE-AMS-QQ-N-290
- Operating Temperature: 221°F [105°C]



NOTE: Aries specializes in custom design and production. In addition to the standard products shown on this page, special materials, platings, sizes, and configurations can be furnished, depending on quantities. Aries reserves the right to change product specifications without notice.

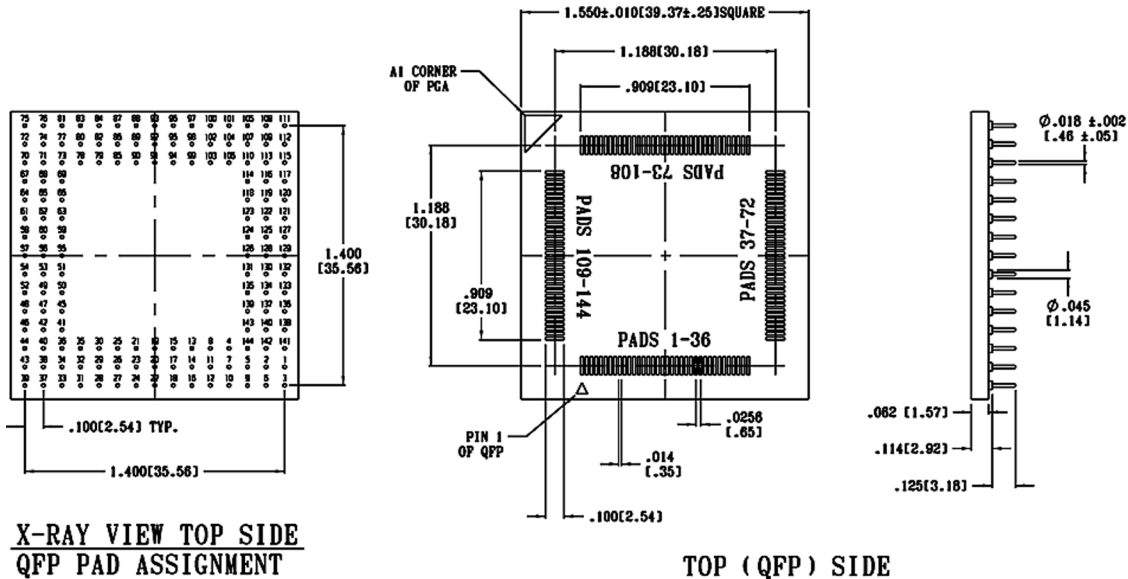
## MOUNTING CONSIDERATIONS

- Suggested PCB Hole Size: 0.062 ± 0.003 [1.58 ± 0.08] diameter
- Will plug into standard PGA sockets

Specify P/N 97-68340  
-or-  
P/N 97-68340-P for  
Panelized Form when ordering

ALL DIMENSIONS: INCHES [MILLIMETERS]

Specify P/N 145-PGM15024-30  
for Wire Wrap PGA socket



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